

SYSTEM AND METHOD FOR USING A PRE-FORMED FILM IN
A TRANSFER MOLDING PROCESS FOR AN INTEGRATED CIRCUIT

ABSTRACT OF THE DISCLOSURE

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10 A system and method is disclosed for using a pre-
formed film in a transfer molding process of the type that
uses a transfer mold to encapsulate portions of an
integrated circuit with a molding compound. A film of
compliant material is pre-formed to conform the shape of
the film to a mold cavity surface of the transfer mold.
The pre-formed film is then placed adjacent to the surfaces
of the mold cavity of the transfer mold. The mold cavity
is filled with molding compound and the integrated circuit
is encapsulated. The pre-formation of the film allows
materials to be used that are not suitable for use with
prior art methods.

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